

MN74HC74/MN74HC74S

Dual D-Type Flip-Flop with Preset and Clear

■ Outline

The MN74HC74/MN74HC74S consists of D-type flip-flop with preset inputs and clear inputs, and has two built-in circuits in one chip.

The respective flip-flop has independent data input, preset input, clear input, clock input, and complementary outputs Q and \bar{Q} . Each input data is transmitted to the output at the rise of the clock pulse. The preset input and the clear input are independent of the clock input, and their active level is "L".

Owing to the silicon gate CMOS process, these flip-flops have realized low power consumption and high noise immunity equivalent to those of a standard CMOS and the operation speed as high as of an LS TTL. The outputs of the respective flip-flop can directly drive ten LS TTL inputs.

To protect the input and output against electrostatic breakdown, a resistor and a diode are used for the V_{CC} and the GND. The pin configuration and the function are the same as those of the standard 54LS/74LS logic family.

■ Truth Table

Input				Output	
PR	CLR	CLK	D	Q	\bar{Q}
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H*	H*
H	H	\nearrow	H	H	L
H	H	\nearrow	L	L	H
H	H	L	X	Q_0	\bar{Q}_0

Note) 1. X : "H" or "L" either will do.

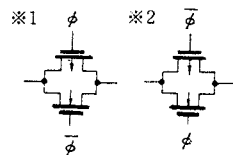
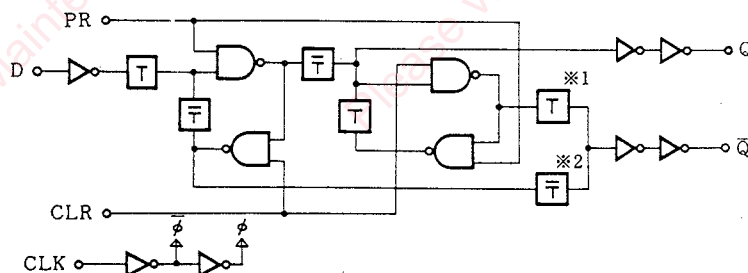
2. \nearrow : Leading in positive direction

3. Q_0 : Q level before input conditions in table are confirmed.

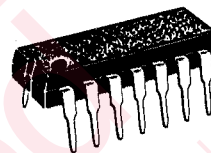
4. \bar{Q}_0 : \bar{Q} level before input conditions in table are confirmed.

5. H* : When preset, clear are "L", Q, \bar{Q} are H but when preset, clear are "H" simultaneously, state of Q, \bar{Q} can not be predicted.

■ Logic Diagram

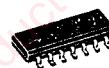


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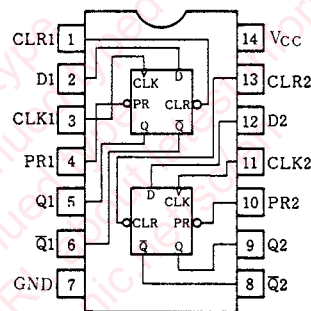
14-pin plastic DIL package

P-2



14-pin PANAFLAT package (SO-14D)

Pin Configuration



■ Absolute Maximum Ratings

Item			Symbol	Rating	Unit
Supply voltage			V_{CC}	$-0.5 \sim +7.0$	V
Input output voltage			V_I, V_O	$-0.5 \sim V_{CC} + 0.5$	V
Input protective diode current			I_{IK}	± 20	mA
Output parasitic diode current			I_{OK}	± 20	mA
Output current			I_O	± 25	mA
Supply current			I_{CC}, I_{GND}	± 50	mA
Storage temperature			T_{stg}	$-65 \sim +150$	°C
Power dissipation	MN74HC74	$T_a = -40 \sim +60^\circ\text{C}$	P_D	400	mW
		$T_a = +60 \sim +85^\circ\text{C}$		Decrease to 200mW at the rate of 8mW/°C	
	MN74HC74S	$T_a = -40 \sim +60^\circ\text{C}$	P_D	275	mW
		$T_a = +60 \sim +85^\circ\text{C}$		Decrease to 200mW at the rate of 3.8mW/°C	

■ Recommended Operating Conditions

Item	Symbol	$V_{CC}(V)$	Rating	Unit
Operating power supply voltage	V_{CC}		1.4~6.0	V
Input output voltage	V_I, V_O		$0 \sim V_{CC}$	V
Operating temperature	T_A		$-40 \sim +85$	°C
Input rise, fall time	t_r, t_f	2.0	0~1000	ns
		4.5	0~500	ns
		6.0	0~400	ns

■ DC Characteristics (GND=0V)

Item	Symbol	V _{CC} (V)	Test Condition			Temperature					Unit
			V _I	V _O	Unit	Ta=25°C			Ta=-40~+85°C		
						min.	typ.	max.	min.	max.	
Input voltage high level	V _{IH}	2.0				1.5			1.5		V
		4.5				3.15			3.15		
		6.0				4.2			4.2		
Input voltage low level	V _{IL}	2.0						0.3		0.3	V
		4.5						0.9		0.9	
		6.0						1.2		1.2	
Output voltage high level	V _{OH}	2.0		-20.0	μA	1.9	2.0		1.9		V
		4.5	V _{IH}	-20.0	μA	4.4	4.5		4.4		
		6.0	or	-20.0	μA	5.9	6.0		5.9		
		4.5	V _{IL}	-4.0	mA	3.92			3.84		
		6.0		-5.2	mA	5.48			5.34		
Output voltage low level	V _{OL}	2.0		20.0	μA		0.0	0.1		0.1	V
		4.5	V _{IH}	20.0	μA		0.0	0.1		0.1	
		6.0	or	20.0	μA		0.0	0.1		0.1	
		4.5	V _{IL}	4.0	mA			0.26		0.33	
		6.0		5.2	mA			0.26		0.33	
Input leakage current	I _I	6.0	V _I =V _{CC} or GND					±0.1		±1.0	μA
Static supply current	I _{CC}	6.0	V _I =V _{CC} or GND, I _O =0					4.0		40.0	μA

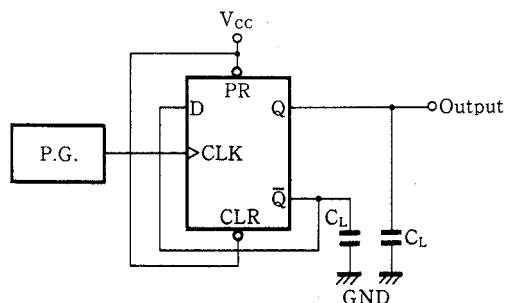
■ AC Characteristics (GND=0V, Input transition time ≤ 6ns, C_L=50pF)

Item	Symbol	V _{CC} (V)	Test Condition	Temperature					Unit
				Ta=25°C			Ta=-40~+85°C		
				min.	typ.	max.	min.	max.	
Output rise time	t _{TLH}	2.0			25	75		95	ns
		4.5			8	15		19	
		6.0			7	13		16	
Output fall time	t _{THL}	2.0			20	75		95	ns
		4.5			7	15		19	
		6.0			6	13		16	
Propagation time CLK→Q, \overline{Q} (L→H)	t _{PLH}	2.0			32	150		190	ns
		4.5			14	30		38	
		6.0			11	26		33	
Propagation time CLK→Q, \overline{Q} (H→L)	t _{PHL}	2.0			32	150		190	ns
		4.5			14	30		38	
		6.0			11	26		33	
Propagation time PR, CLR→Q, \overline{Q} (L→H)	t _{PLH}	2.0			32	150		190	ns
		4.5			14	30		38	
		6.0			10	26		33	
Propagation time PR, CLR→Q, \overline{Q} (H→L)	t _{PHL}	2.0			32	150		190	ns
		4.5			13	30		38	
		6.0			10	26		33	
Minimum set-up time	t _{su}	2.0			7	75		95	ns
		4.5			4	15		19	
		6.0			3	13		16	
Minimum hold time	t _h	2.0			—	0		0	ns
		4.5			—	0		0	
		6.0			—	0		0	
Minimum pulse width PR, CLR	t _w	2.0			26	75		95	ns
		4.5			9	15		19	
		6.0			7	13		16	
Minimum recovery time PR, CLR	t _{rem}	2.0			5	75		95	ns
		4.5			4	15		19	
		6.0			2	13		16	
Maximum clock frequency	f _{max}	2.0		6	20		4		MHz
		4.5		30	58		24		
		6.0		35	70		28		

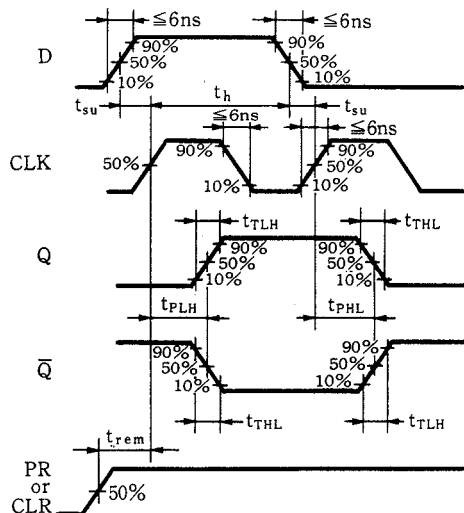
• Switching time measuring circuit and waveforms

(1) t_{TLH} , t_{THL} , t_{su} , f_{max} , t_{PLH}/t_{PHL} (CLK→Q, \bar{Q}), t_{rem} , t_h

1. Measuring circuit

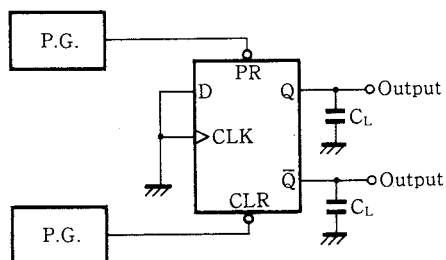


2. Switching waveforms

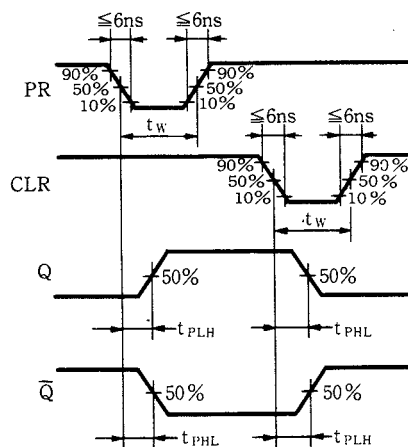


(2) t_{PLH}/t_{PHL} (PR, CLR→Q, \bar{Q}), t_w (PR, CLR)

1. Measuring circuit



2. Switching waveforms



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